Dual Inverter

The NLX2G04 MiniGate $^{\rm m}$ is an advanced high-speed CMOS dual inverter in ultra-small footprint.

The NLX2G04 input and output structures provide protection when voltages up to 7.0 V are applied, regardless of the supply voltage.

Features

- High Speed: $t_{PD} = 1.8 \text{ ns (Typ)} @ V_{CC} = 5.0 \text{ V}$
- Low Power Dissipation: $I_{CC} = 1 \mu A$ (Max) at $T_A = 25^{\circ}C$
- Power Down Protection Provided on inputs
- Balanced Propagation Delays
- Overvoltage Tolerant (OVT) Input and Output Pins
- Ultra-Small Packages
- These are Pb-Free Devices

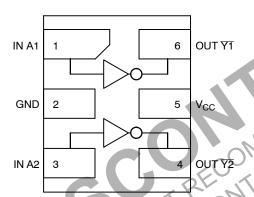


Figure 1. Pinout (Top View)



Figure 2. Logic Symbol

PIN ASSIGNMENT

1	IN A1	
2	GND	
3	IN A2	
4	OUT Y2	
5	V _{CC}	
6	OUT Y1	

FUNCTION TABLE

Α	₹
L	H
H	L



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MARKING DIAGRAMS







UDFN6 1.0 x 1.0 CASE 517BX





UDFN6 1.2 x 1.0 CASE 517AA





UDFN6 1.45 x 1.0 CASE 517AQ



Q M Device MarkingDate Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet.

MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
V _{CC}	DC Supply Voltage		−0.5 to +7.0	V
V _{IN}	DC Input Voltage		−0.5 to +7.0	V
V _{OUT}	DC Output Voltage		−0.5 to +7.0	V
I _{IK}	DC Input Diode Current	V _{IN} < GND	-50	mA
l _{ok}	DC Output Diode Current	V _{OUT} < GND	-50	mA
I _O	DC Output Source/Sink Current		±50	mA
I _{CC}	DC Supply Current Per Supply Pin		±100	mA
I _{GND}	DC Ground Current per Ground Pin		±100	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C
TJ	Junction Temperature Under Bias		150	°C
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating Oxygen	Index: 28 to 34	UL 94 V-0 @ 0.125 in	
I _{LATCHUP}	Latchup Performance Above V _{CC} and Below GND at 1	25°C (Note 2)	±500	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	Positive DC Supply Voltage	1.65	5.5	V
V _{IN}	Digital Input Voltage	0	5.5	V
V _{OUT}	Output Voltage	0	5.5	V
T _A	Operating Free-Air Temperature	-55	+125	°C
Δt/ΔV	Input Transition Rise or Fall Rate $ \begin{array}{c} V_{CC} = 2.5 \ V \pm 0.2 \ V \\ V_{CC} = 3.3 \ V \pm 0.3 \ V \\ V_{CC} = 5.0 \ V \pm 0.5 \ V \\ \end{array} $	0 0 0	20 10 5	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

^{2.} Tested to EIA / JESD78.

DC ELECTRICAL CHARACTERISTICS

			V _{CC}	7	A = 25°C	;	T _A = +	-85°C	T _A = -5		
Symbol	Parameter	Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V _{IH}	Low-Level Input Voltage		1.65-1.95	0.75 x V _{CC}			0.75 x V _{CC}		0.75 x V _{CC}		V
	voltage		2.3 to 5.5	0.70 x V _{CC}			0.70 x V _{CC}		0.70 x V _{CC}		
V _{IL}	Low-Level Input Voltage		1.65-1.95			0.25 x V _{CC}		0.25 x V _{CC}		0.25 x V _{CC}	V
	voltage		2.3 – 5.5			0.30 x V _{CC}		0.30 x V _{CC}		0.30 x V _{CC}	
V _{OH}	High– Level Output	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -100 \mu A$	1.65 – 5.5	V _{CC} - 0.1	V _{CC}		V _{CC} - 0.1		V _{CC} - 0.1		V
	Voltage	$\begin{aligned} &V_{\text{IN}} = V_{\text{IH}} \text{ or } V_{\text{IL}} \\ &I_{\text{OH}} = -4 \text{ mA} \\ &I_{\text{OH}} = -8 \text{ mA} \\ &I_{\text{OH}} = -12 \text{ mA} \\ &I_{\text{OH}} = -16 \text{ mA} \\ &I_{\text{OH}} = -24 \text{ mA} \\ &I_{\text{OH}} = -32 \text{ mA} \end{aligned}$	1.65 2.3 2.7 3.0 3.0 4.5	1.29 1.9 2.2 2.4 2.3 3.8	1.52 2.1 2.4 2.7 2.5 4.0		1.29 1.9 2.2 2.4 2.3 3.8		1.29 1.9 2.2 2.4 2.3 3.8	IGN	
V _{OL}	Low-Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 100 \mu A$	1.65 – 5.5			0.1	R	0:1		0.1	V
	voltage	$\begin{aligned} &V_{IN} = V_{IH} \text{ or } V_{IL} \\ &I_{OH} = -4 \text{ mA} \\ &I_{OH} = -8 \text{ mA} \\ &I_{OH} = -12 \text{ mA} \\ &I_{OH} = -16 \text{ mA} \\ &I_{OH} = -24 \text{ mA} \\ &I_{OH} = -32 \text{ mA} \end{aligned}$	1.65 2.3 2.7 3.0 3.0 4.5		0.08 0.2 0.22 0.28 0.38 0.42	0.24 0.3 0.4 0.4 0.55 0.55	ons	0.24 0.3 0.4 0.4 0.55 0.55		0.24 0.3 0.4 0.4 0.55 0.55	
I _{IN}	Input Leakage Current	0 ≤ V _{IN} ≤ 5.5 V	0 to 5.5	SITA		±0.1		±1.0		±1.0	μΑ
I _{OFF}	Power-Off Output Leakage Current	V _{IN} or V _{OUT} = 5.5 V	SE	ATIV		1.0		10		10	μΑ
I _{CC}	Quiescent Supply Current	$0 \le V_{IN} \le V_{CC}$	5,5			1.0		10		10	μΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

AC ELECTRICAL CHARACTERISTICS (Input t_r = t_f = 3.0 nS)

		V _{CC}	Test	7	Γ _A = 25°(T _A = - to +1		
Symbol	Parameter	(V)	Condition	Min	Тур	Max	Min	Max	Unit
t _{PLH} , t _{PHL}	Propagation Delay, Input A to Output \overline{Y}	1.65	$R_L = 1 M\Omega$, $C_L = 15 pF$	1.8	2.3	9.2	1.8	11	ns
		1.8	$R_L = 1 M\Omega$, $C_L = 15 pF$	1.8	4.4	7.6	1.2	8.4	
		2.3-2.7	$R_L = 1 M\Omega$, $C_L = 15 pF$	1.2	3.0	5.1	1.2	5.6	
		3.0-3.6	$R_L = 1 M\Omega$, $C_L = 15 pF$	0.8	2.2	3.4	0.8	3.8	
			$R_L = 500 \Omega,$ $C_L = 50 pF$	1.2	2.9	4.5	1.2	5.0	
		4.5–5.5	$R_L = 1 M\Omega$, $C_L = 15 pF$	0.5	1.8	2.8	0.5	3.1	
			$R_L = 500 \Omega$, $C_L = 50 pF$	0.8	2.3	3.6	0.8	4.0	
C _{IN}	Input Capacitance	5.5	$V_{IN} = 0 \text{ V or } V_{CC}$		2.5	N.			pF
C _{PD}	Power Dissipation Capacitance (Note 3)	3.3 5.5	10 MHz V _{IN} = 0 V or V _{CC}		9 11				pF

^{3.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC} · C_{PD} is used to determine the no-load dynamic power consumption: P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

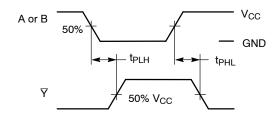
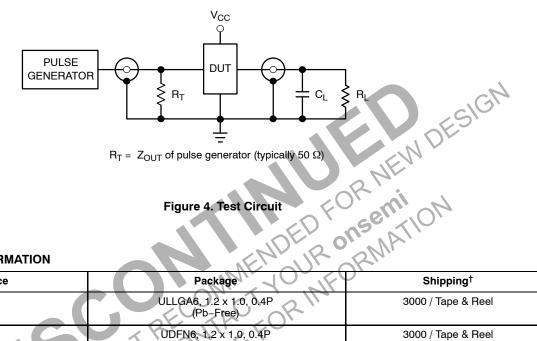


Figure 3. Switching Waveforms

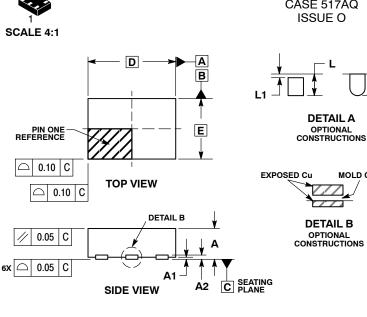


ORDERING INFORMATION

Device	Package	Shipping [†]
NLX2G04BMX1TCG	ULLGA6, 1.2 x 1.0, 0.4P (Pb-Free)	3000 / Tape & Reel
NLX2G04MUTCG	UDFN6, 1.2 x 1.0, 0.4P (Pb-Free)	3000 / Tape & Reel
NLX2G04AMUTCG	UDFN6, 1.45 x 1.0, 0.5P (Pb-Free)	3000 / Tape & Reel
NLX2G04CMUTCG	UDFN6, 1.0 x 1.0, 0.35P (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.





6X L

6X b

Ф

0.10 | C | A | B

0.05 C NOTE 3

UDFN6, 1.45x1.0, 0.5P CASE 517AQ **ISSUE O**

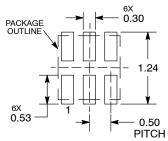
MOLD CMPD

DATE 15 MAY 2008

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

	MILLIMETERS				
DIM	MIN MAX				
Α	0.45	0.55			
A1	0.00	0.05			
A2	0.07 REF				
b	0.20	0.30			
D	1.45	BSC			
Е	1.00	BSC			
Ф	0.50 BSC				
L	0.30	0.40			
L1		0.15			

MOUNTING FOOTPRINT



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*

BOTTOM VIEW

е



Χ = Specific Device Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present.

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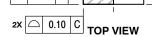
0.10

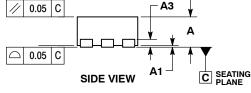


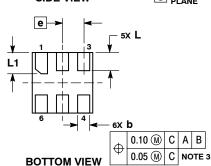
UDFN6, 1x1, 0.35P CASE 517BX **ISSUE O**

DATE 18 MAY 2011







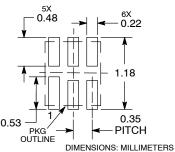


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP. 4. PACKAGE DIMENSIONS EXCLUSIVE OF
- BURRS AND MOLD FLASH.

	MILLIMETERS				
DIM	MIN	MAX			
Α	0.45	0.55			
A1	0.00	0.05			
A3	0.13 REF				
b	0.12	0.22			
D	1.00	BSC			
E	1.00	BSC			
е	0.35 BSC				
L	0.25	0.35			
L1	0.30	0.40			

RECOMMENDED **SOLDERING FOOTPRINT***



*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



X = Specific Device Code

M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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ULLGA6, 1.2x1.0, 0.4P CASE 613AÉ **ISSUE A**

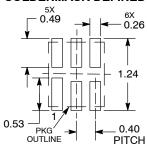
DATE 06 FEB 2008

NOTES:

- DIMENSIONING AND TOLERANCING PER
- In Dimensioning AND TOLERANGING FER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSION 6 APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND
- 0.30 mm FROM THE TERMINAL TIP.
 A MAXIMUM OF 0.05 PULL BACK OF THE
 PLATED TERMINAL FROM THE EDGE OF THE
 PACKAGE IS ALLOWED.

	MILLIMETERS			
DIM	MIN	MAX		
Α		0.40		
A1	0.00	0.05		
ь	0.15	0.25		
ם	1.20	BSC		
Е	1.00	BSC		
е	0.40 BSC			
L	0.25	0.35		
11	0.35	0.45		

MOUNTING FOOTPRINT SOLDERMASK DEFINED*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

	PIN ONE REFERENCE O.10 C	E ↓
	○ 0.10 C	TOP VIEW
	// 0.05 C	↓ <u>↓</u> A
6X	□ 0.05 C	SIDE VIEW SEATING PLANE
	↓ L1 ↑	e 5x L NOTE 4

BOTTOM VIEW

D

В

0.10 C A B

0.05 C NOTE 3

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